

B1 - making a microrelief for each microcomponent by mechanical machining of the substrate, the mechanical machining comprising moving at least one tool translationally and parallel to the substrate; and

- cutting out the microcomponents in the substrate such that individual microcomponents or groups of microcomponents are separated from each other.

Sub 12 16. (Amended) A method according to Claim 14, wherein making a microrelief is performed to an extent of obtaining optical quality of the microrelief. (12)

B1 17. (Amended) A method according to Claim 14, wherein the microrelief is made with a single tool moved at the surface of the substrate.

18. (Amended) A method according to Claim 14, wherein the microrelief is made by several tools working simultaneously and/or in succession.

19. (Amended) A method according to Claim 14, wherein the microcomponents are microprisms.

Sub 13 20. (Amended) A method according to Claim 14, wherein the microprisms are made by a "V" profile abrasive blade.

Add new Claims 22- as follows:

21. (New) A method according to Claim 19, the saw having a blade with plane and parallel faces, or having at least an inclined face.

22. (New) A method according to Claim 14, wherein making a microrelief consists of passing a blade having a die which does not have abrasive grit therein, said